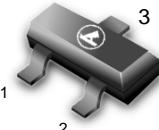
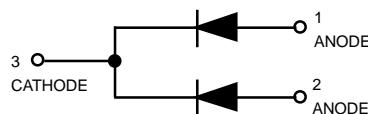


# Monolithic Dual Switching Diode

**LBAV74LT1**

CASE 318-08, STYLE 9  
SOT-23 (TO-236AB)

**DEVICE MARKING**

LBAV74LT1 = JA

**MAXIMUM RATINGS (EACH DIODE)**

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	50	Vdc
Forward Current	$I_F$	200	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	500	mAdc

**THERMAL CHARACTERISTICS**

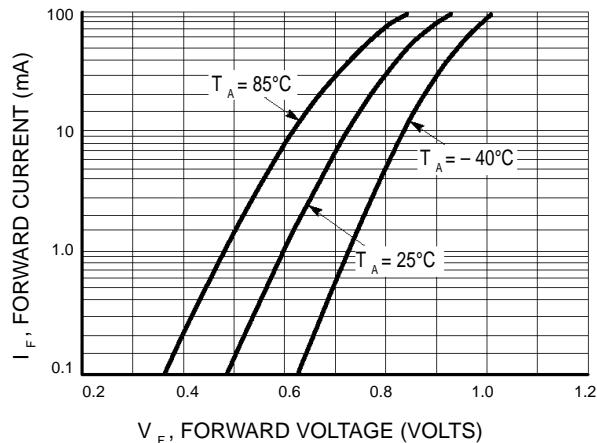
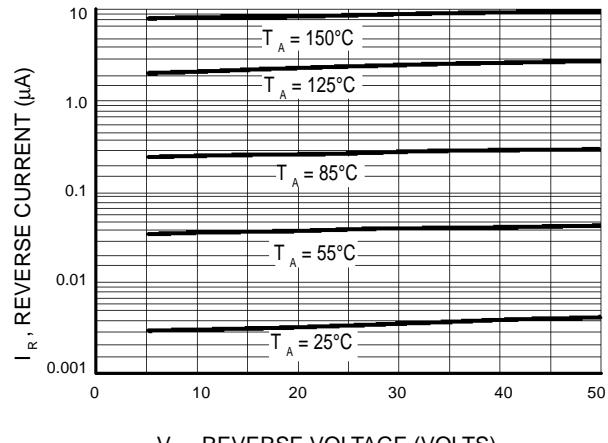
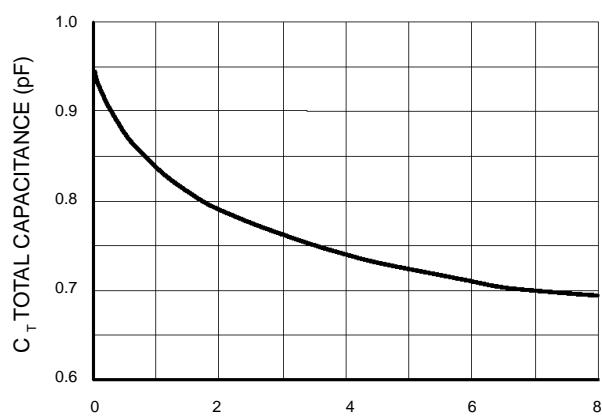
Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board (1) $T_A = 25^\circ\text{C}$	$P_D$	225	mW
Derate above $25^\circ\text{C}$		1.8	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	556	$^\circ\text{C}/\text{W}$
Total Device Dissipation Alumina Substrate, (2) $T_A = 25^\circ\text{C}$	$P_D$	300	mW
Derate above $25^\circ\text{C}$		2.4	$\text{mW}/^\circ\text{C}$
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	-55 to +150	$^\circ\text{C}$

**ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$  unless otherwise noted) ( EACH DIODE )**

Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Reverse Breakdown Voltage ( $I_{(BR)} = 5.0 \mu\text{Adc}$ )	$V_{(BR)}$	50	—	Vdc
Reverse Voltage Leakage Current ( $V_R = 50 \text{ Vdc}, T_J = 125^\circ\text{C}$ ) ( $V_R = 50 \text{ Vdc}$ )	$I_R$	—	100	$\mu\text{Adc}$
Diode Capacitance ( $V_R = 0, f = 1.0 \text{ MHz}$ )	$C_D$	—	2.0	pF
Forward Voltage ( $I_F = 100 \text{ mAdc}$ )	$V_F$	—	1.0	Vdc
Reverse Recovery Time ( $I_F = I_R = 10 \text{ mA}, I_{R(REO)} = 1.0 \text{ mA}, \text{ measured at } I_R = 1.0 \text{ mA, } R_L = 100\Omega$ )	$t_{rr}$	—	4.0	ns

1. FR-5 = 1.0 x 0.75 x 0.062 in.

2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

**LBAV74LT1**
**Curves Applicable to Each Anode**

**Figure 1. Forward Voltage**

**Figure 3. Leakage Current**

**Figure 3. Capacitance**